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CLAIMS

1. A printed circuit board, comprising:

a base substrate; and

5 an external interconnection terminal

provided on said base substrate,

said external interconnection terminal

comprising a land formed on a front surface of said

base substrate and a metal plate soldered upon said

10 land via a solder layer,

a through-hole being formed in said base

substrate such that said through-hole penetrates

through said land and through said base substrate,

said through-hole being filled with a

15 solder such that said solder in said through-hole

extends in continuation to said solder layer

connecting said metal plate to said land.

2. The printed circuit board as claimed in

20 claim 1, wherein said base substrate carries a second

land on a rear surface thereof so as to oppose to

said land on said front surface, said land on said

front surface and said second land on said rear

surface being connected with each other by said

25 solder filling said through-hole.

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3 . The printed circuit board as claimed in  
claim 1, wherein said through-hole being provided in  
plural numbers in each land.

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4 . The printed circuit board as claimed in  
claim 1, further comprising a solder resist layer on  
said front surface of said base substrate such that  
said solder resist layer covers a peripheral edge  
10 part of said land, said solder resist layer extending  
in continuation to a part of said front surface of  
said base substrate surrounding said land.

5 . The printed circuit board as claimed in  
15 claim 1, further comprising a solder resist layer on  
said land in a part offset from a peripheral edge of  
said land.

6 . The printed circuit board as claimed in  
20 claim 5, wherein said solder resist layer forms a  
pattern dividing an area of said land connected to  
said metal plate by said solder layer into sub-  
regions .

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7 . The printed circuit board as claimed in

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claim 6, wherein said solder resist pattern extends to an outside of said land.

8. The printed circuit board as claimed in  
5 claim 4, wherein there is formed a solder resist pattern in a part of said land offset from said peripheral edge part, said solder resist pattern and said solder resist layer dividing an area of said land soldered to said metal plate by said solder  
10 layer into sub-regions.

9. The printed circuit board as claimed in  
claim 1, wherein said solder resist layer is used also for covering an interconnection pattern formed  
15 on said base substrate.

10. The printed circuit board as claimed in  
claim 1, wherein said metal plate has an area larger than an area of said land, said metal plate being  
20 placed on said land so as to cover entirety of said land.

11. A printed circuit board comprising:  
a base substrate; and  
25 an external interconnection terminal

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provided on said base substrate,

    said external interconnection terminal comprising a land formed on a surface of said base substrate and a metal plate soldered upon said land  
5    via a solder layer,

    wherein there is provided a solder resist layer covering a peripheral edge part of said land such that said solder resist layer extends in continuation to a part of said surface of said base  
10   substrate surrounding said land.

12. The printed circuit board as claimed in claim 11, further comprising a solder resist pattern on an area of said land offset from said peripheral  
15   edge part.

13. The printed circuit board as claimed in claim 12, wherein said solder resist pattern divides an area of said land soldered to said metal plate by  
20   said solder layer into plural sub-regions.

14. The printed circuit board as claimed in claim 12, wherein said solder resist layer and said solder resist pattern divide an area of said land  
25   soldered to said metal plate by said solder layer

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into plural sub-regions.

15. The printed circuit board as claimed in  
claim 11, wherein said solder resist layer is used  
5 also for covering an interconnection pattern formed  
on said base substrate.

16. The printed circuit board as claimed in  
claim 11, wherein said metal plate has an area larger  
10 than an area of said land, said metal plate being  
placed on said land so as to cover entirety of said  
land.

17. A printed circuit assembly, comprising:  
15 a printed circuit substrate comprising: a  
base substrate; and an external interconnection  
terminal provided on said base substrate, said  
external interconnection terminal comprising a land  
formed on a front surface of said base substrate and  
20 a metal plate soldered upon said land via a solder  
layer, a through-hole being formed in said base  
substrate being such that said through-hole  
penetrates through said land and through said base  
substrate, said through-hole being filled with a  
25 solder such that said solder in said through-hole

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extends in continuation to said solder layer connecting said metal plate to said land; and an electronic component mounted on said printed circuit board.

5 18. A printed circuit assembly, comprising:  
a printed circuit board comprising: a base substrate; and an external interconnection terminal provided on said base substrate, said external interconnection terminal comprising a land formed on  
10 a surface of said base substrate and a metal plate soldered upon said land via a solder layer, wherein there is provided a solder resist layer covering a peripheral edge part of said land such that said solder resist layer extends in continuation to a part  
15 of said surface of said base substrate surrounding said land; and  
an electronic component mounted on said printed circuit board.

20 19. An electronic apparatus, comprising:  
a printed circuit substrate comprising: a base substrate; and an external interconnection terminal provided on said base substrate, said external interconnection terminal comprising a land  
25 formed on a front surface of said base substrate and

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a metal plate soldered upon said land via a solder layer, a through-hole being formed in said base substrate being such that said through-hole penetrates through said land and through said base

5 substrate, said through-hole being filled with a solder such that said solder in said through-hole extends in continuation to said solder layer connecting said metal plate to said land;

an electronic component mounted on said  
10 printed circuit board; and

an electronic device having a metal plate terminal, said electronic device being connected to said printed circuit board by connecting said metal plate terminal to said metal plate of said external  
15 interconnection terminal by way of spot welding.

20. The electronic apparatus as claimed in  
claim 19, wherein said metal plate terminal of said  
electronic device and said metal plate of said  
20 external interconnection terminal comprises any of  
nickel or a nickel alloy.

21. An electronic apparatus as claimed in  
claim 19, wherein said electronic apparatus comprises  
25 a secondary battery pack including therein a

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secondary battery as said electronic device, said printed circuit board carrying a charging control circuit of said secondary battery as said electronic component .

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22. An electronic apparatus, comprising:  
a printed circuit board comprising: a base substrate; and an external interconnection terminal provided on said base substrate, said external  
10 interconnection terminal comprising a land formed on a surface of said base substrate and a metal plate soldered upon said land via a solder layer, wherein there is provided a solder resist layer covering a peripheral edge part of said land such that said  
15 solder resist layer extends in continuation to a part of said surface of said base substrate surrounding said land;  
an electronic component mounted on said printed circuit board; and  
20 an electronic device having a metal plate terminal, said electronic device being connected to said printed circuit board by connecting said metal plate terminal to said metal plate of said external interconnection terminal by way of spot welding.

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23. The electronic apparatus as claimed in  
claim 22, wherein said metal plate terminal of said  
electronic device and said metal plate of said  
external interconnection terminal comprises any of  
5 nickel or a nickel alloy.

24. An electronic apparatus as claimed in  
claim 22, wherein said electronic apparatus comprises  
a secondary battery pack including therein a  
10 secondary battery as said electronic device, said  
printed circuit board carrying a charging control  
circuit of said secondary battery as said electronic  
component .